

SG Series



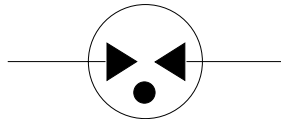
Description

Littelfuse SG series GDT offers high surge ratings in a miniature package. It's designed for surface mounting on PCB with small size 4.5x3.2x2.7mm. Low insertion loss is perfectly suited to broadband equipment applications. The capacitance does not vary with voltage, and will not cause operational problems with ADSL2+, where capacitance variation across Tip and Ring is undesirable. These devices are extremely robust and are able to divert a 1000A pulse without destruction.

Agency Approvals

| Agency | Agency File Number |
|--------|--------------------|
| | E128662 |

2 Electrode GDT Graphical Symbol



Features

- RoHS compliant and Lead-free
- GHz working frequency
- Excellent stability on multiple pulse duty cycle
- Excellent response to fast rising transients.
- Ultra Low Insertion Loss
- 1-2KA surge capability tested with 8/20µS pulse as defined by IEC 61000-4-5
- Ultra small devices offered in a variety of mounting lead forms
- Non-Radioactive
- Low capacitance (<1pF)
- Voltage Ranges 75V to 600V
- UL Recognized
- Conforms to ITU-T K12, IEC 61000-4-5
- Square Outline

Additional Information



Datasheet



Resources



Samples

Applications

- Communication equipment
- CATV equipment
- Test equipment
- Data lines
- Power supplies
- Telecom SLIC protection
- Broadband equipment
- ADSL equipment, including ADSL2+
- XDSL equipment
- Satellite and CATV equipment
- General telecom equipment

Electrical Characteristics

| Part Number | Device Specifications (at 25°C) | | | | | | | | | | Life Ratings | | |
|-------------|---------------------------------|------|------|---------------------------------------|---|-----------------------|---------------------|-------------------|--------------------------------|--------------|--|---|--|
| | DC Breakdown in Volts (@100V/s) | | | Impulse Breakdown in Volts (@100V/μs) | Impulse Breakdown In Volts (@1 Kv/μsec) | Insulation Resistance | Capacitance (@1MHz) | Arc Voltage (@1A) | Glow to Arc Transition Current | Glow Voltage | Nominal AC Discharge Current (x10 @50Hz) | Nominal Impulse Discharge Current (x10 @8/20μs) | Nominal Impulse Discharge Current (10/1000μs 100 cycles) |
| | Min. | Typ. | Max. | Max. | Min. | Max. | | | | | | | |
| SG75 | 52 | 75 | 98 | 500 | 650 | >1GΩ (at 50VDC) | <1 pf | ~10 V | ~1.0 A | ~60 V | 2 A | 2kA | 10 A |
| SG90 | 63 | 90 | 117 | 500 | 600 | | | | | | | | |
| SG150 | 105 | 150 | 195 | 500 | 600 | | | | | | | | |
| SG200* | 140 | 200 | 260 | 550 | 700 | >1GΩ (at 100VDC) | <0.8 pf | ~12 V | ~0.5 A | ~140 V | 2.5 A | | |
| SG230 | 172 | 230 | 288 | 650 | 800 | | | | | | | | |
| SG300 | 225 | 300 | 375 | 700 | 850 | | | | | | | | |
| SG300Q | 210 | 300 | 390 | 580 | 650 | >1GΩ (at 50VDC) | <0.8 pf | ~20 V | ~0.8 A | ~140 V | NA* | | |
| SG350 | 263 | 350 | 437 | 750 | 900 | | | | | | | | |
| SG350Q | 263 | 350 | 437 | 600 | 700 | | | | | | | | |
| SG400 | 300 | 400 | 500 | 800 | 950 | >1GΩ (at 100VDC) | <1 pf | ~10 V | ~1.0 A | ~60 V | 2 A | | |
| SG420 | 315 | 420 | 525 | 800 | 1000 | | | | | | | | |
| SG420Q | 315 | 420 | 525 | 650 | 750 | | | | | | | | |
| SG450Q | 370 | 450 | 500 | 680 | 750 | >1GΩ (at 100VDC) | <0.5 pf | ~20 V | ~0.1 A | ~140 V | 1 A | | |
| SG500Q | 400 | 500 | 600 | 950 | 1050 | | | | | | | | |
| SG600Q | 450 | 600 | 750 | 1100 | 1200 | | | | | | | | |

* Specification is not applicable for quick response (SGxxxQ) version of product
+ Not UL Recognized

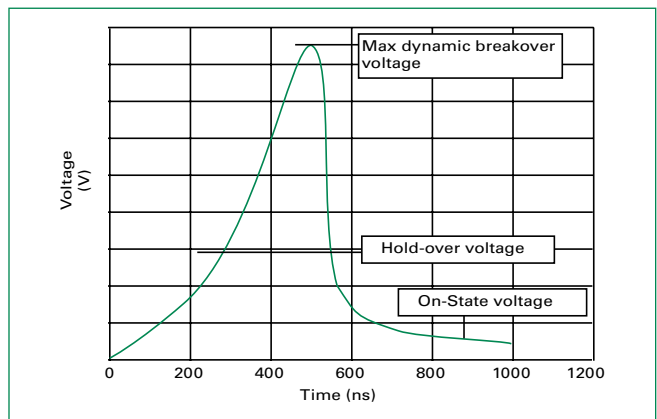
Product Characteristics

| | |
|--|--|
| Materials | Device Tin Plated 17.5±12.5 Microns Construction Ceramic Insulator. |
| Storage and Operational Temperature | -40 to +90 °C |

Typical Insertion Loss

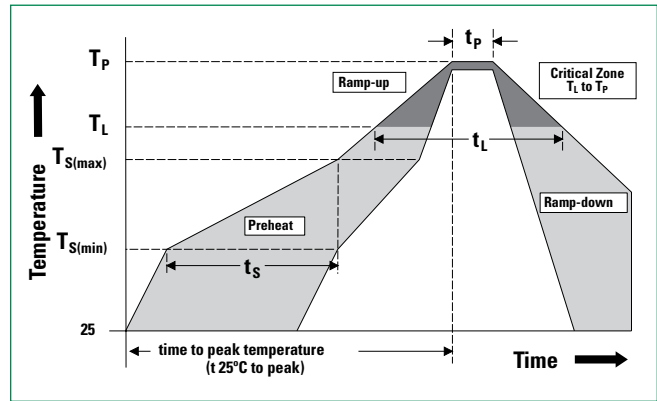
| | |
|--|---------------------|
| | @ 1.0 GHz = 0.01 dB |
| | @ 1.4GHz = 0.1 dB |
| | @ 1.8 GHz = 0.53 dB |
| | @ 2.1 GHz = 0.81 dB |
| | @ 2.45 GHz = 1 dB |
| | @ 2.8 GHz = 1.2 dB |
| | @ 3.1 GHz = 1.5 dB |
| | @ 3.5 GHz = 2.1 dB |

Voltage vs. Time Characteristic

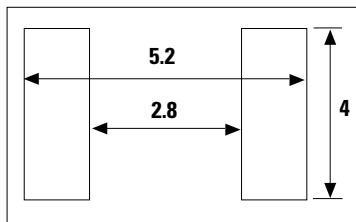
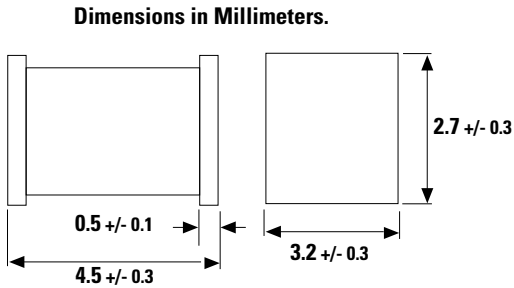


Soldering Parameters - Reflow Soldering (Surface Mount Devices)

| | | |
|--|------------------------------------|-------------------------|
| Reflow Condition | | Pb – Free assembly |
| Pre Heat | - Temperature Min ($T_{s(min)}$) | 150°C |
| | - Temperature Max ($T_{s(max)}$) | 200°C |
| | - Time (Min to Max) (t_s) | 60 – 180 secs |
| Average ramp up rate (Liquidus Temp (T_L) to peak) | | 3°C/second max |
| $T_{s(max)}$ to T_L - Ramp-up Rate | | 5°C/second max |
| Reflow | - Temperature (T_L) (Liquidus) | 217°C |
| | - Temperature (t_L) | 60 – 150 seconds |
| Peak Temperature (T_p) | | 260 ^{+0/-5} °C |
| Time within 5°C of actual peak Temperature (t_p) | | 10 – 30 seconds |
| Ramp-down Rate | | 6°C/second max |
| Time 25°C to peak Temperature (T_p) | | 8 minutes Max. |
| Do not exceed | | 260°C |

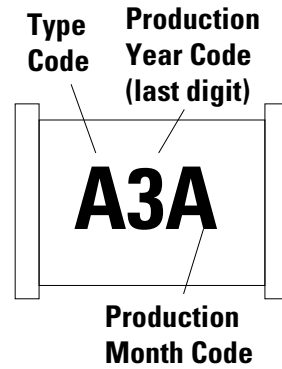


Device Dimensions



Recommended Soldering Pad Layout

Device Marking



| Type Code | |
|-----------|--------|
| A | SG75 |
| B | SG90 |
| C | SG150 |
| D | SG230 |
| E | SG300 |
| F | SG300Q |
| G | SG350 |
| H | SG350Q |
| I | SG400 |
| J | SG420 |
| K | SG420Q |
| L | SG450Q |
| M | SG500Q |
| N | SG600Q |
| O | SG200 |

| Month Code | |
|------------|-----------|
| A | January |
| B | February |
| C | March |
| D | April |
| E | May |
| F | June |
| G | July |
| H | August |
| I | September |
| J | October |
| K | November |
| L | December |